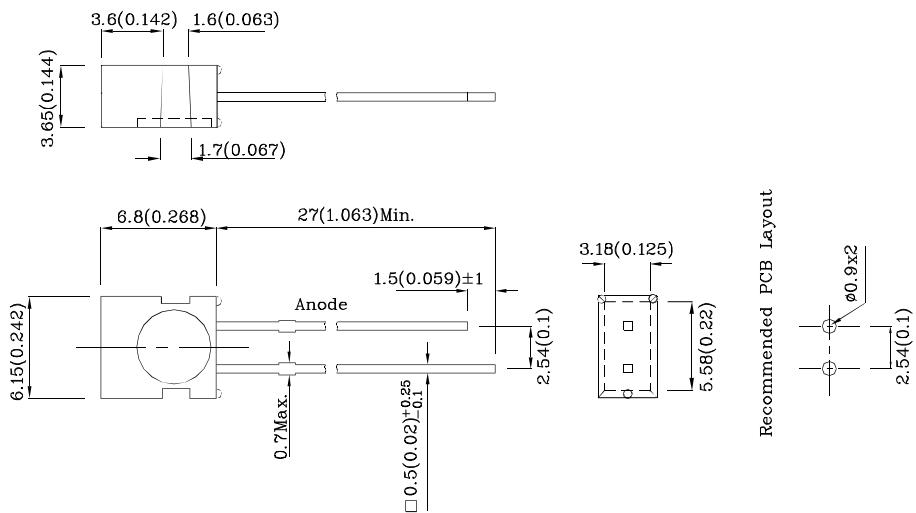


Features

- Reliable & robust
- Low power consumption
- RoHS compliant


Package Schematics

Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
3. Specifications are subject to change without notice.

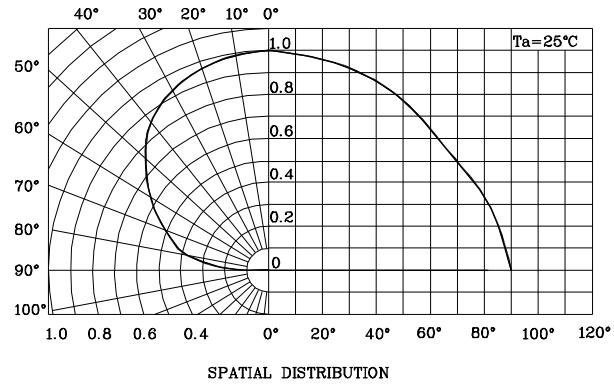
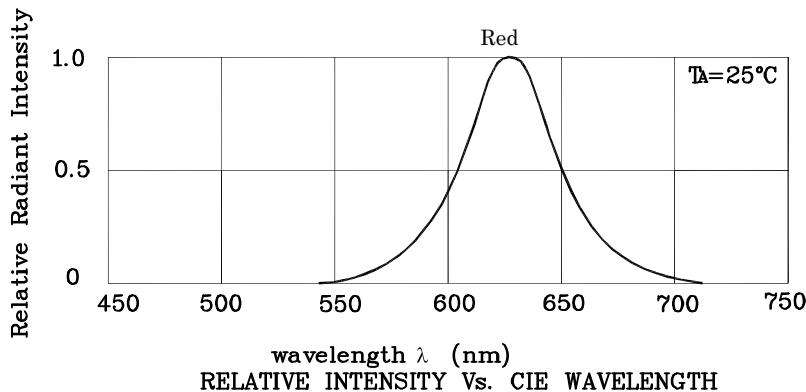
| Absolute Maximum Ratings (T _A =25°C) | | Red (GaAsP/GaP) | Unit | |
|--|---------------------|---------------------------|-------------|--|
| Reverse Voltage | V _R | 5 | V | |
| Forward Current | I _F | 30 | mA | |
| Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width | i _{fs} | 160 | mA | |
| Power Dissipation | P _D | 75 | mW | |
| Operating Temperature | T _A | -40 ~ +85 | °C | |
| Storage Temperature | T _{stg} | -40 ~ +85 | | |
| Lead Solder Temperature [2mm Below Package Base] | 260°C For 3 Seconds | | | |
| Lead Solder Temperature [5mm Below Package Base] | 260°C For 5 Seconds | | | |

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

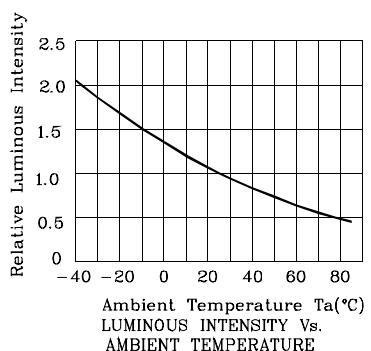
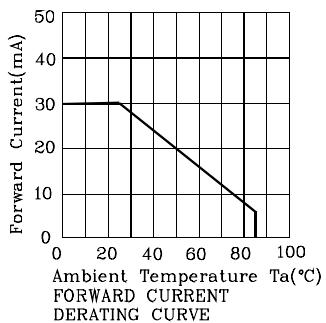
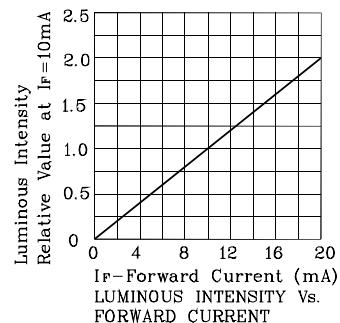
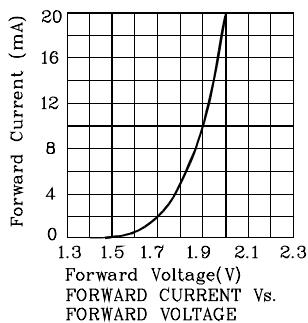
| Operating Characteristics (T _A =25°C) | | Red (GaAsP/GaP) | Unit |
|--|-----------------|---------------------------|-------------|
| Forward Voltage (Typ.) (I _F =10mA) | V _F | 1.9 | V |
| Forward Voltage (Max.) (I _F =10mA) | V _F | 2.5 | V |
| Reverse Current (Max.) (V _R =5V) | I _R | 10 | uA |
| Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =10mA) | λ P | 627* | nm |
| Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =10mA) | λ D | 617* | nm |
| Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA) | $\Delta\lambda$ | 45 | nm |
| Capacitance (Typ.) (V _F =0V, f=1MHz) | C | 15 | pF |

| Part Number | Emitting Color | Emitting Material | Lens-color | Luminous Intensity CIE127-2007* (I _F =10mA) mcd | Wavelength CIE127-2007* nm λ P | Viewing Angle 20 1/2 |
|----------------|-------------------|----------------------|--------------|---|---|----------------------------|
| XEUR21D | Red | GaAsP/GaP | Red Diffused | 3 2* | 5 3.8* | 627* 140° |

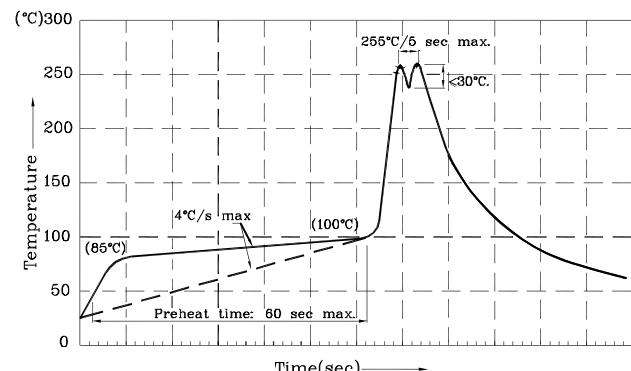
*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.



❖ Red



Wave Soldering Profile For Thru-Hole Products (Pb-Free Components)



Notes:

1. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
2. Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).
3. Do not apply stress to the epoxy resin while the temperature is above 85°C.
4. Fixtures should not incur stress on the component when mounting and during soldering process.
5. SAC 305 solder alloy is recommended.
6. No more than one wave soldering pass.

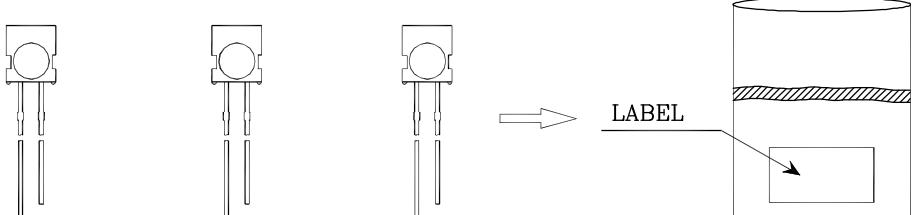
Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

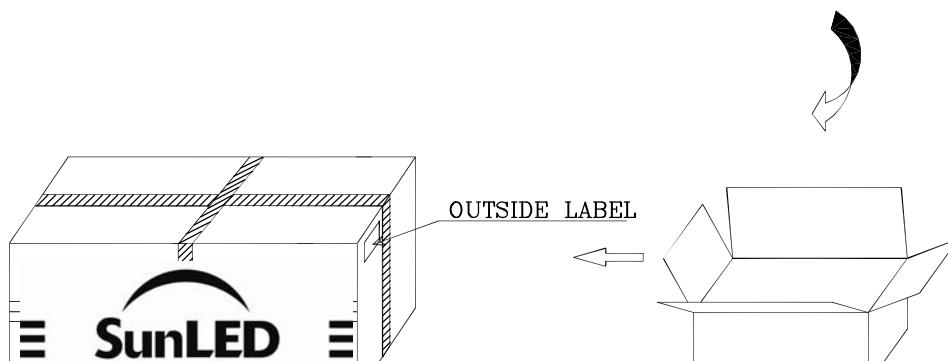
1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

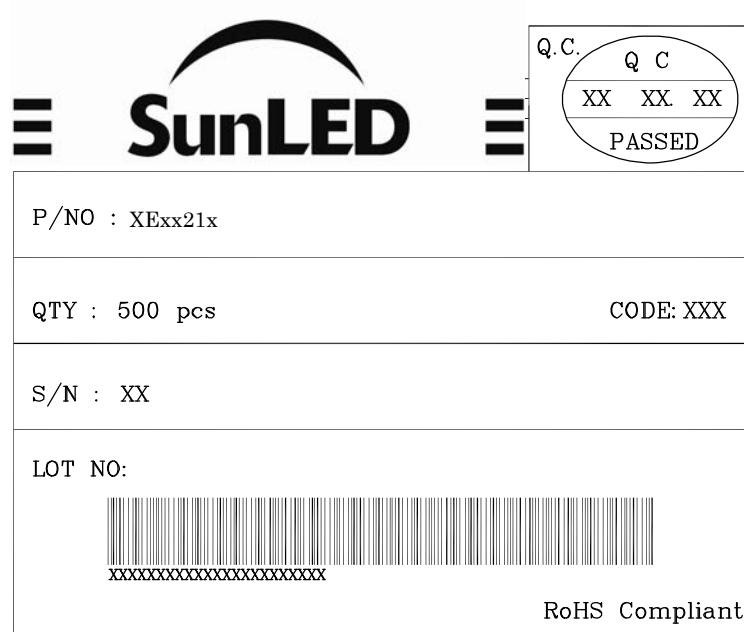
PACKING & LABEL SPECIFICATIONS



500 PCS/ Bag



14K / Box



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